

**Notice of References Cited**

Application/Control No.

09/942,643

Applicant(s)/Patent Under  
Reexamination  
MATSUSHITA ET AL.

Examiner

Leigh Marie Garbowski

Art Unit

2825

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	B	US-5,644,687	07-1997	Agonafer et al.	345/419
	C	US-6,334,115 B1	12-2001	Kuribayashi et al.	705/27
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	M	US-			

**FOREIGN PATENT DOCUMENTS**

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**NON-PATENT DOCUMENTS**

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	U	Free et al., "Recent Advances in Thermal/Flow Simulation: Integrating Thermal Analysis into the Mechanical Design Process," Eleventh IEEE SEMI-THERM Symposium, 1995, pages 136-145.
	V	Hubing et al., "EMC Applications of EMAP-2: A 3D Finite Element Modeling Code," IEEE Int'l Symposium on Electromagnetic Compatibility, 1993, pages 279-283.
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	X	Yook et al., "Application of System-Level EM Modeling to High-Speed Digital IC Packages and PCB's," IEEE Trans. on Microwave Theory and Techniques, Vol. 45, No. 10, 1997, pages 1847-1856.

\*A copy of this reference is not being furnished with this Office action. (See MPEP § 707.05(a).)  
Dates in MM-YYYY format are publication dates. Classifications may be US or foreign.